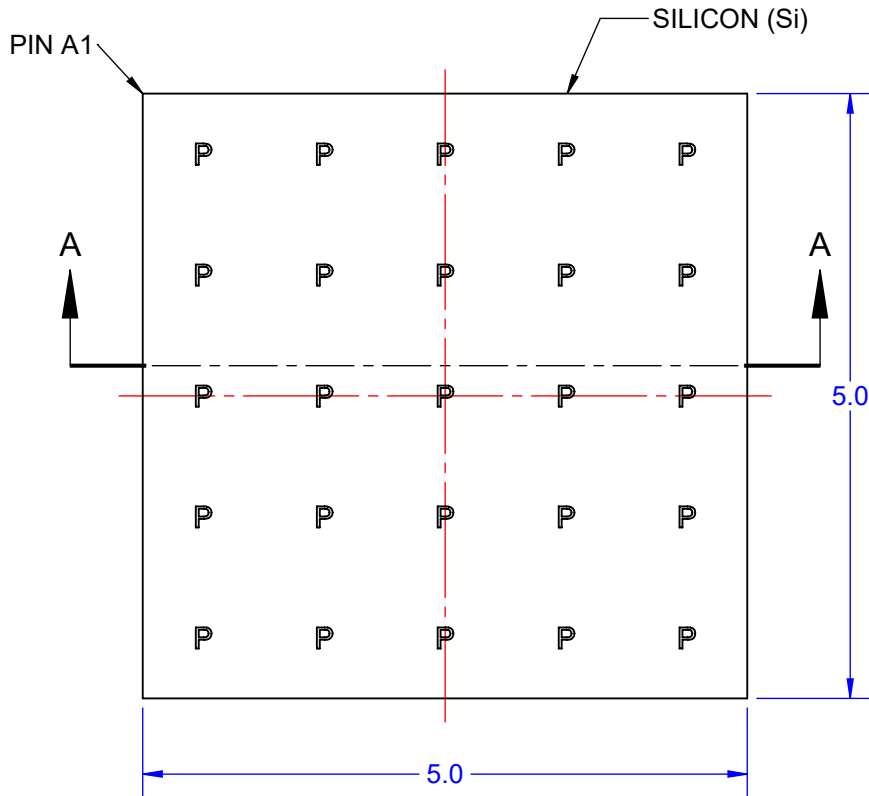
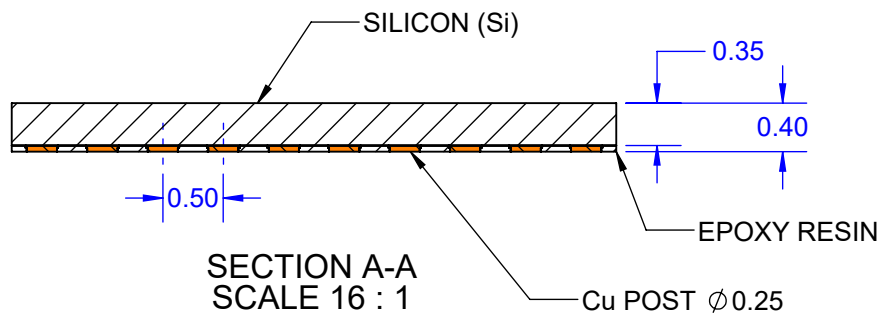
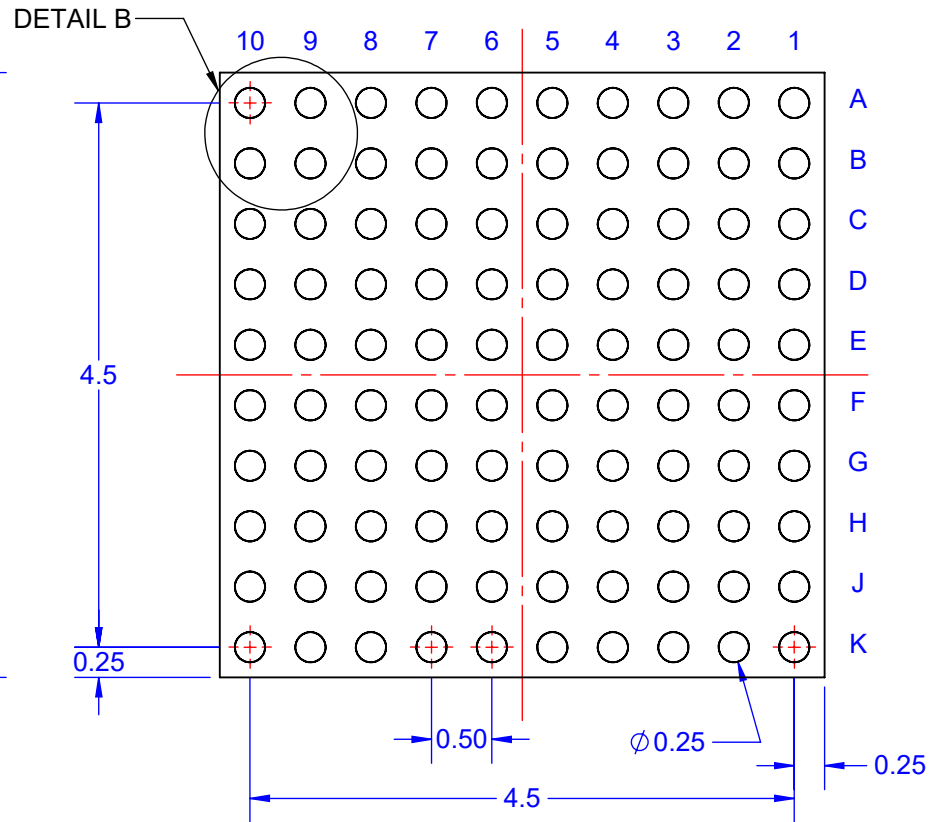


TOP VIEW



PAD VIEW



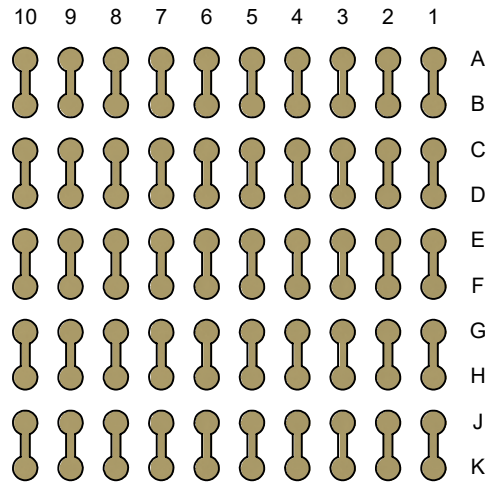
SECTION A-A
SCALE 16 : 1

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu (50 μ m THICK).
 3) PAD Cu DIAMETER: ϕ 0.25
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 2).

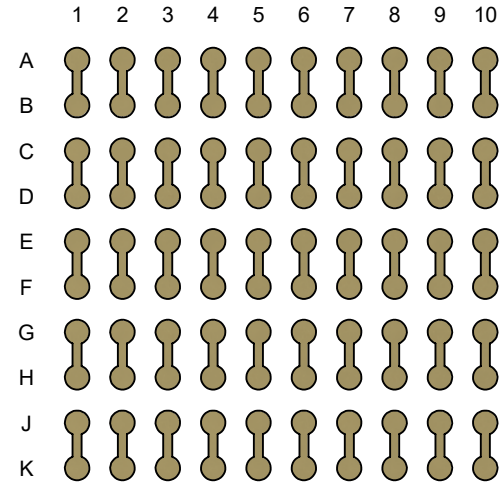
APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	6/18/2021				
ENG M. Hart	6/18/2021	TITLE eWLP100T.5-DC108D 100-PAD P=0.5mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		1:16	A	751089	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 9
REVISED					

DAISY CHAIN PATTERN

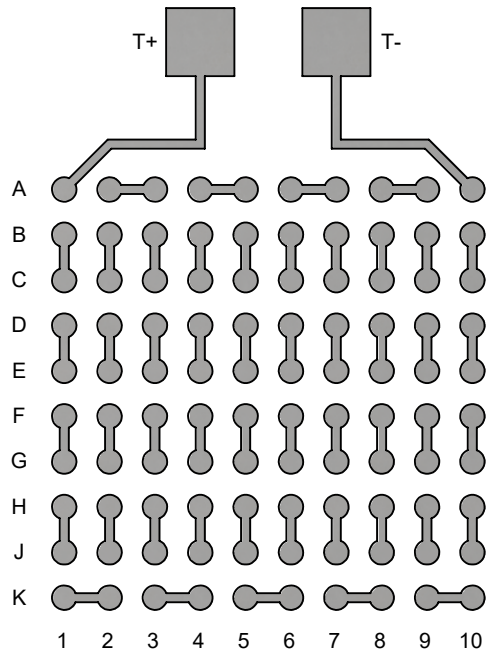
PAD VIEW



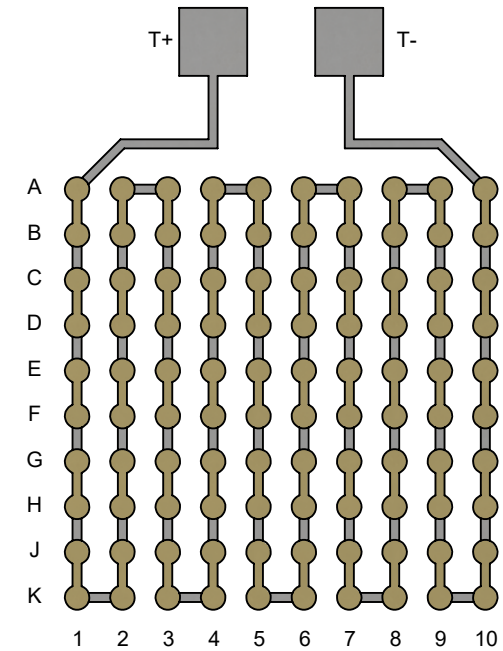
**BOTTOM SIDE
(TOP X-RAY VIEW)**



TEST VEHICLE BOARD



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**



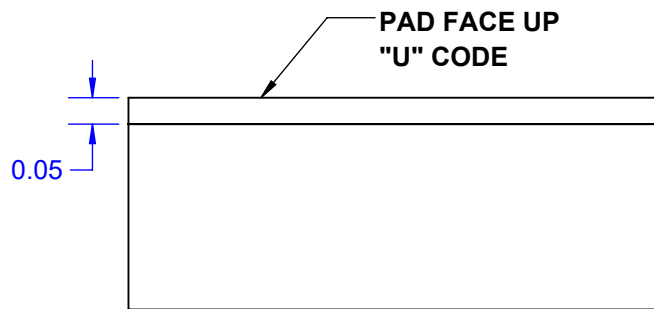
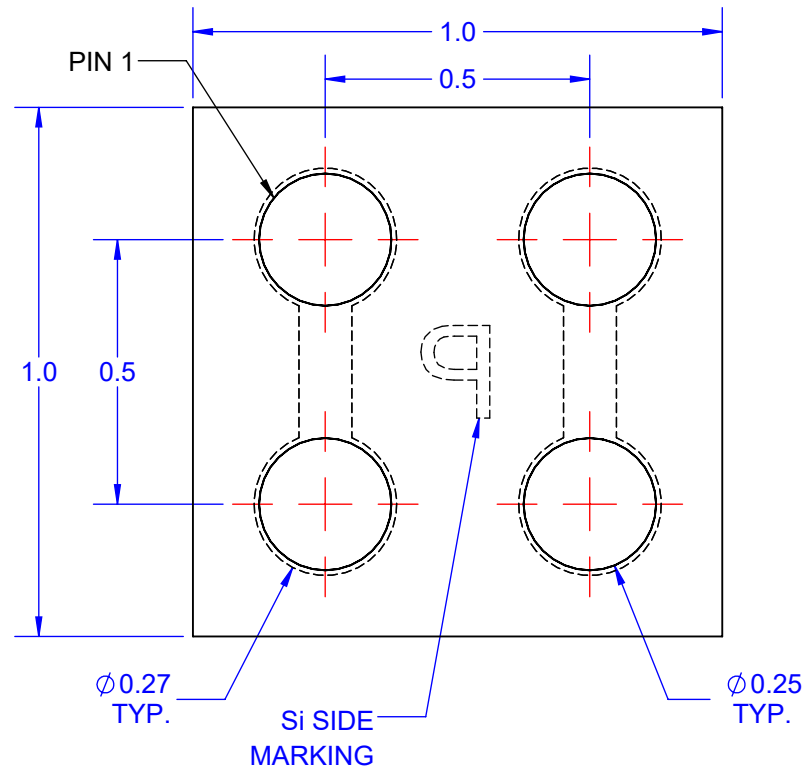
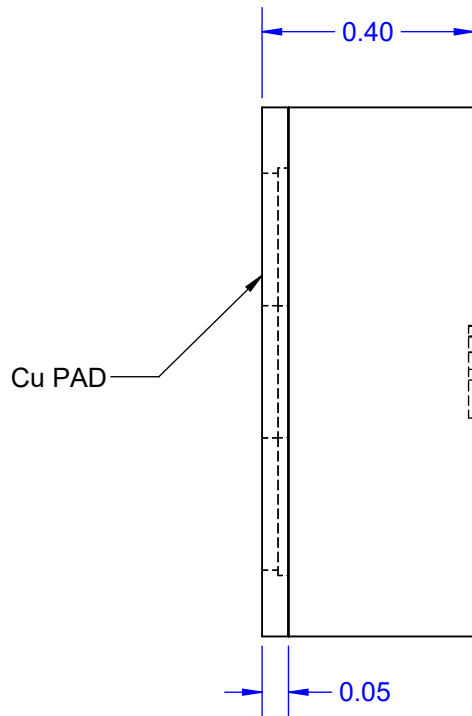
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu PAD DIAMETER 0.25mm (9.8 mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9 mil).

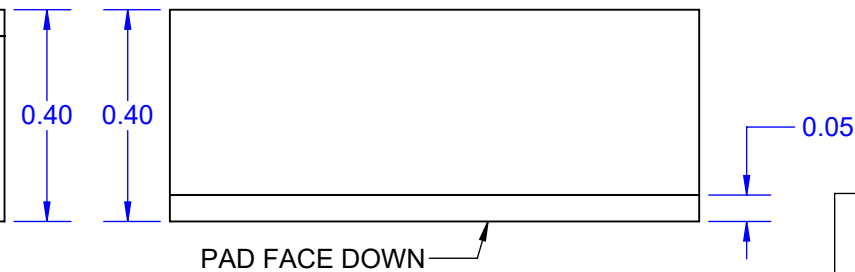
TopLine[®]			
TITLE		eWLP100T.5-DC108D 100-PAD P=0.5mm	
SCALE	SIZE	DRAWING NO.	REV
12:1	A	751089	A
DO NOT SCALE DRAWING			SHEET 2 OF 9

DETAIL B COPPER POST

COPPER PAD ROUND POST



PAD FACE DOWN "D" CODE



SIDE VIEW

PAD FACE DOWN

TopLine[®]

TITLE eWLP100T.5-DC108D
100-PAD P=0.5mm

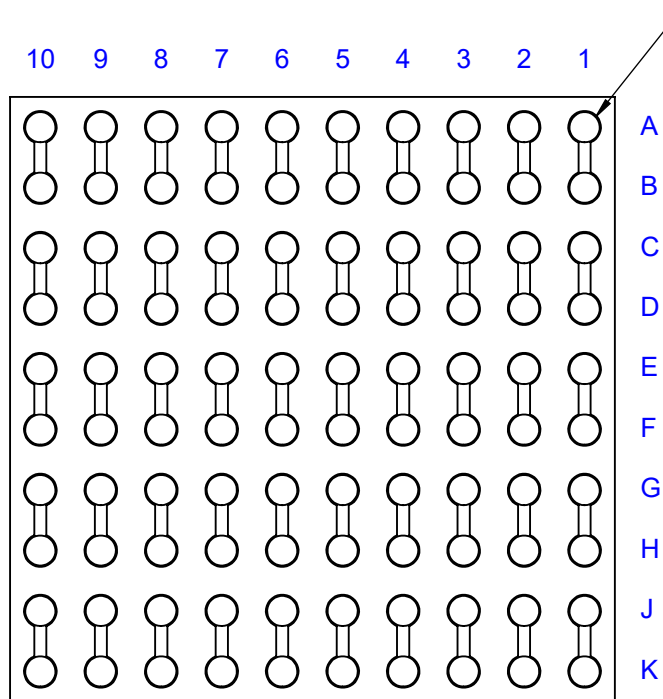
SCALE 70:1	SIZE A	DRAWING NO. 751089	REV A
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DO NOT SCALE DRAWING

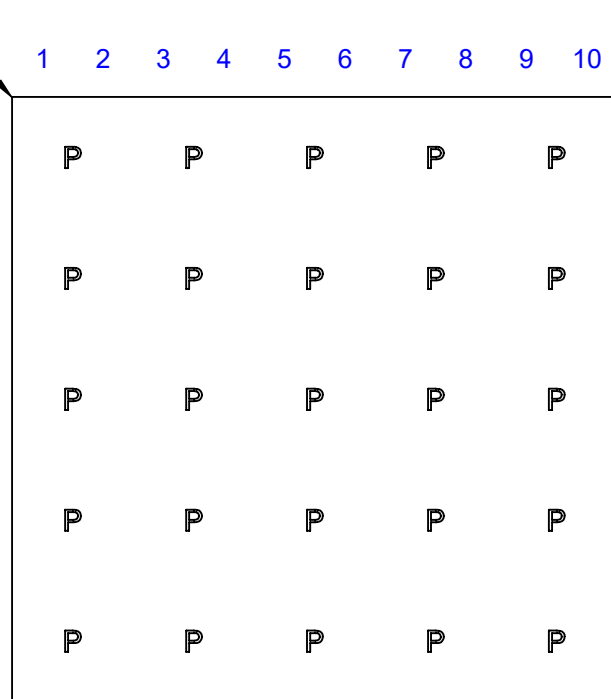
SHEET 3 OF 9

DAISY CHAIN PATTERN ROUND PADS

PAD VIEW



TOP MARKING



TopLine[®]

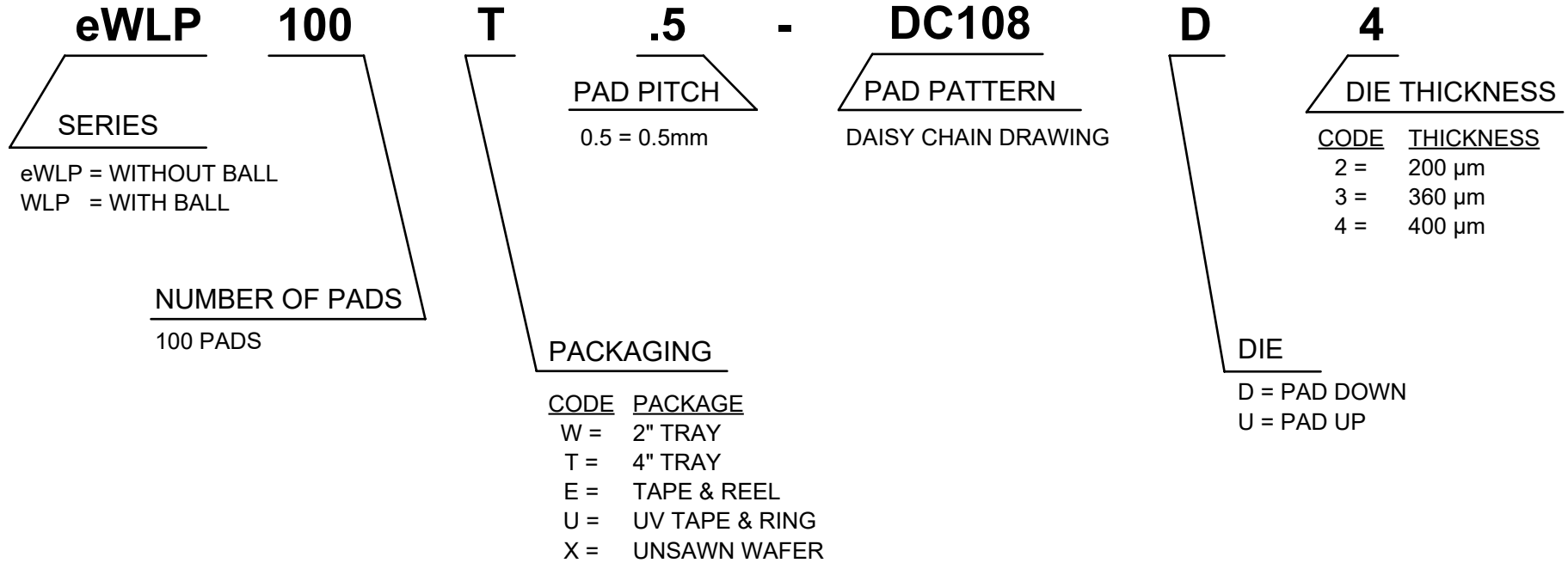
TITLE eWLP100T.5-DC108D
100-PAD P=0.5mm

SCALE 16:1	SIZE A	DRAWING NO. 751089	REV A
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DO NOT SCALE DRAWING

SHEET 4 OF 9

PART NUMBERING SYSTEM



TopLine®			
TITLE eWLP100T.5-DC108D 100-PAD P=0.5mm			
SCALE NONE	SIZE A	DRAWING NO. 751089	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 9

DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PADS					
651087	eWLP100W.5-DC108U2	200 µm	ROUND	UP	2-INCH TRAY
651088	eWLP100W.5-DC108D2	200 µm	ROUND	DOWN	2-INCH TRAY
651089	eWLP100T.5-DC108U2	200 µm	ROUND	UP	4-INCH TRAY
651080	eWLP100T.5-DC108D2	200 µm	ROUND	DOWN	4-INCH TRAY
651081	eWLP100E.5-DC108D2	200 µm	ROUND	DOWN	TAPE & REEL
651082	eWLP100E.5-DC108D2	200 µm	ROUND	DOWN	CUT TAPE
651083	eWLP100U.5-DC108U2	200 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
651085	eWLP100X.5-DC108U2	200 µm	ROUND	UP	UNSAWN WAFER

DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PADS					
751087	eWLP100W.5-DC108U4	400 µm	ROUND	UP	2-INCH TRAY
751088	eWLP100W.5-DC108D4	400 µm	ROUND	DOWN	2-INCH TRAY
751089	eWLP100T.5-DC108U4	400 µm	ROUND	UP	4-INCH TRAY
751080	eWLP100T.5-DC108D4	400 µm	ROUND	DOWN	4-INCH TRAY
751081	eWLP100E.5-DC108D4	400 µm	ROUND	DOWN	TAPE & REEL
751082	eWLP100E.5-DC108D4	400 µm	ROUND	DOWN	CUT TAPE
751083	eWLP100U.5-DC108U4	400 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
751085	eWLP100X.5-DC108U4	400 µm	ROUND	UP	UNSAWN WAFER

TopLine[®]

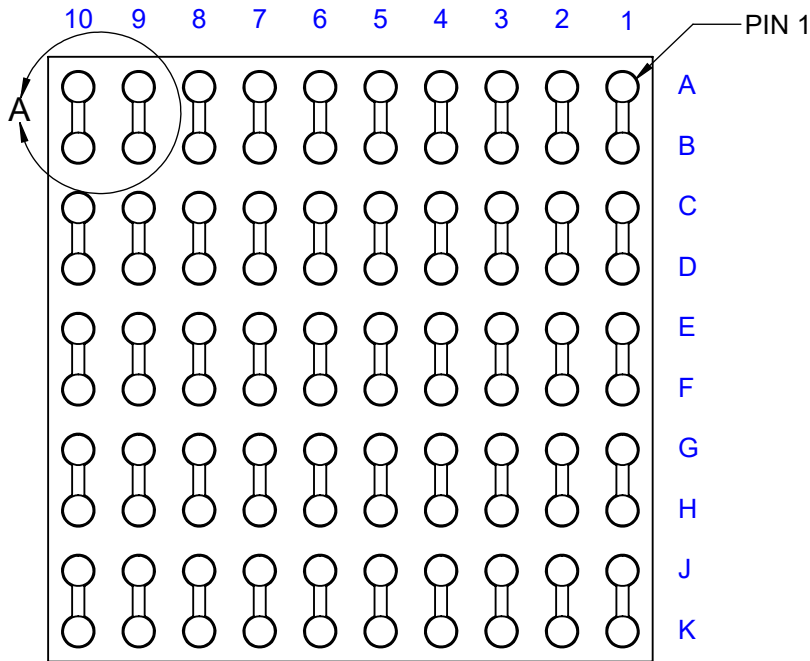
TITLE eWLP100T.5-DC108D
100-PAD P=0.5mm

SCALE NONE	SIZE A	DRAWING NO. 751089	REV A
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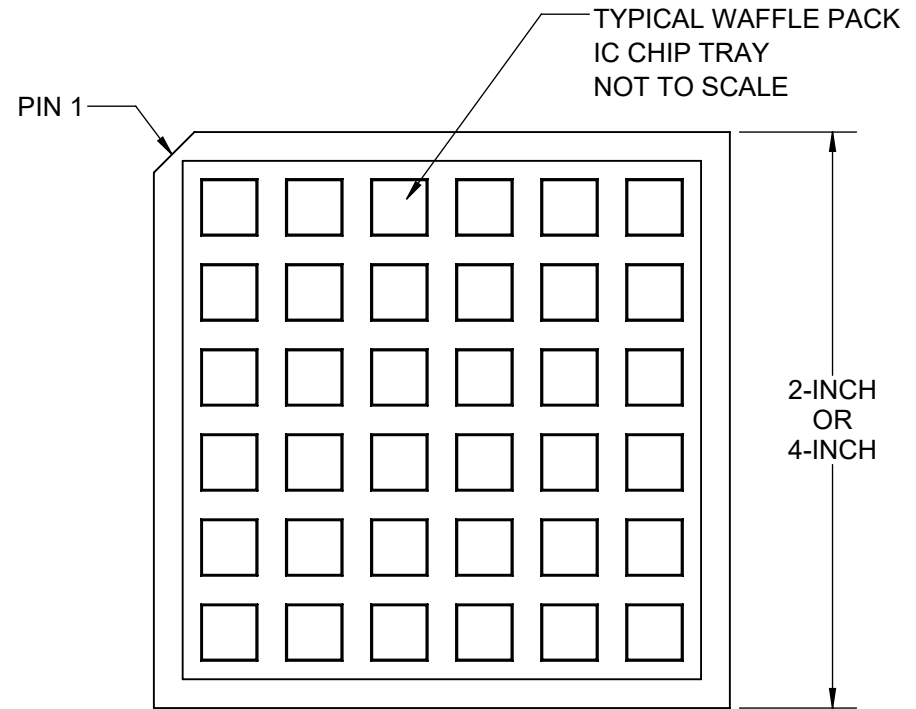
DO NOT SCALE DRAWING

SHEET 6 OF 9

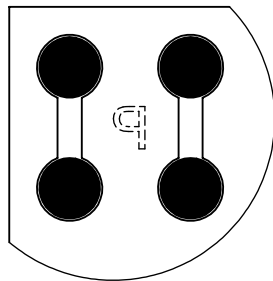
**DAISY CHAIN
PAD VIEW**



**WAFFLE PACK
PAD SIDE FACE UP**



NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE CHIP



DETAIL A
SCALE 32:1
ROUND PAD

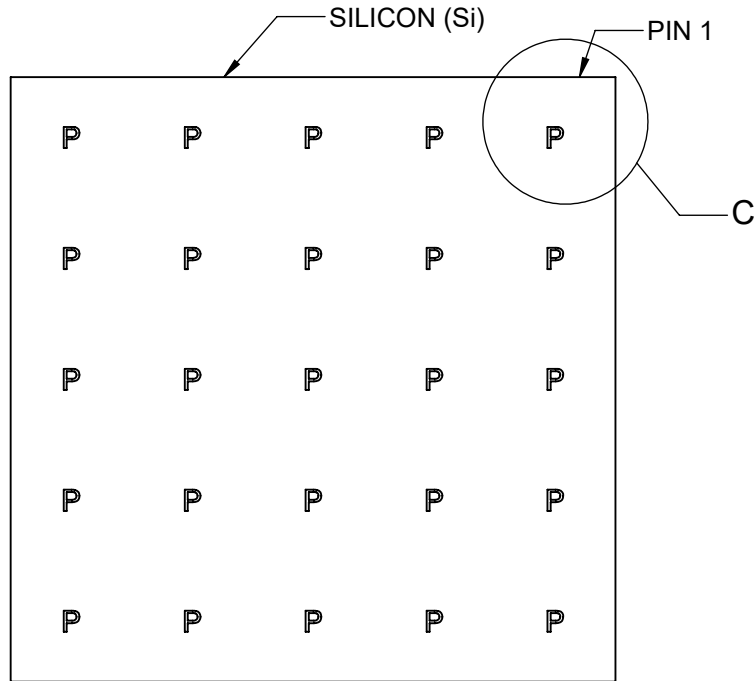
Notes: (Unless Otherwise Specified).

- 1) TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

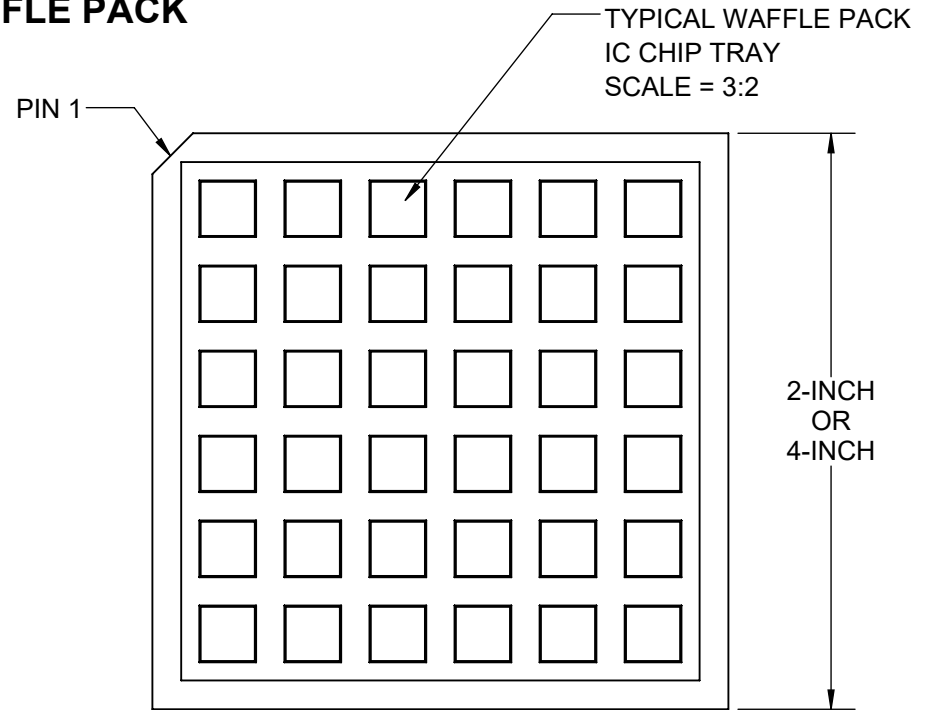
TopLine®			
TITLE eWLP100T.5-DC108D 100-PAD P=0.5mm			
SCALE 16:1	SIZE A	DRAWING NO. 751089	REV A
DO NOT SCALE DRAWING			SHEET 7 OF 9

TOP VIEW



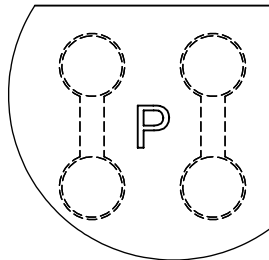
EXAMPLE OF ORIENTATION OF MARKINGS ON eWLP

PAD SIDE DOWN ORIENTATION WAFFLE PACK



NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP

DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN ORIENTATION

DETAIL C
SCALE 32 : 1
ROUND PAD

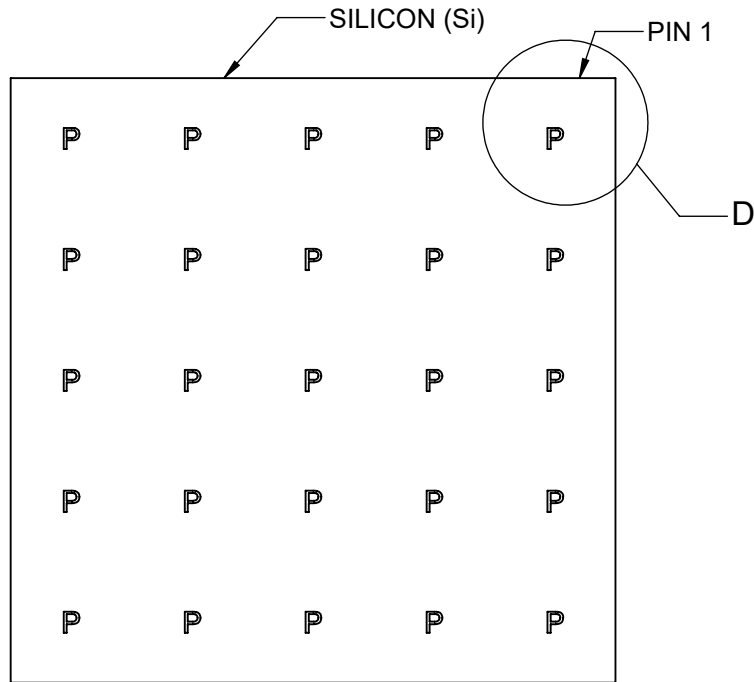
Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

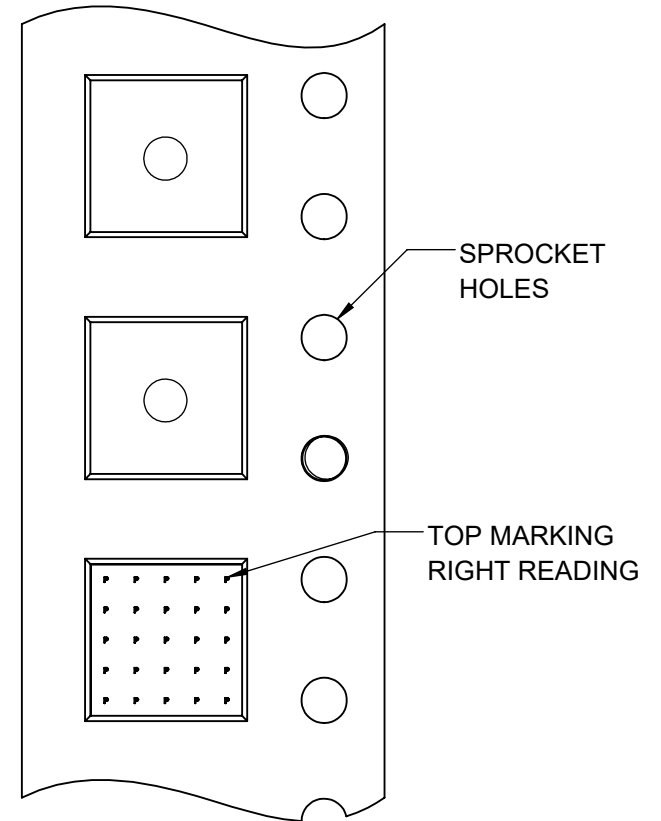
TopLine[®]			
TITLE eWLP100T.5-DC108D 100-PAD P=0.5mm			
SCALE 16:1	SIZE A	DRAWING NO. 751089	REV A
DO NOT SCALE DRAWING			SHEET 8 OF 9

TOP VIEW



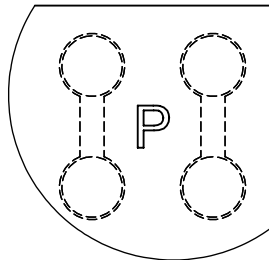
EXAMPLE OF ORIENTATION OF MARKINGS ON eWLP

eWLP ORIENTATION TAPE AND REEL



DIRECTION OF FEED

DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN ORIENTATION

DETAIL D NOT TO SCALE ROUND PAD

Notes: (Unless Otherwise Specified).

- 1) TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIDE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (PADS) SIDE.

MARKING CODE	
PITCH	LETTER
0.3 MM	A
0.4 MM	F
0.5 MM	P

TopLine[®]			
TITLE eWLP100T.5-DC108D 100-PAD P=0.5mm			
SCALE 16:1	SIZE A	DRAWING NO. 751089	REV A
DO NOT SCALE DRAWING			SHEET 9 OF 9